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## FIG. IA

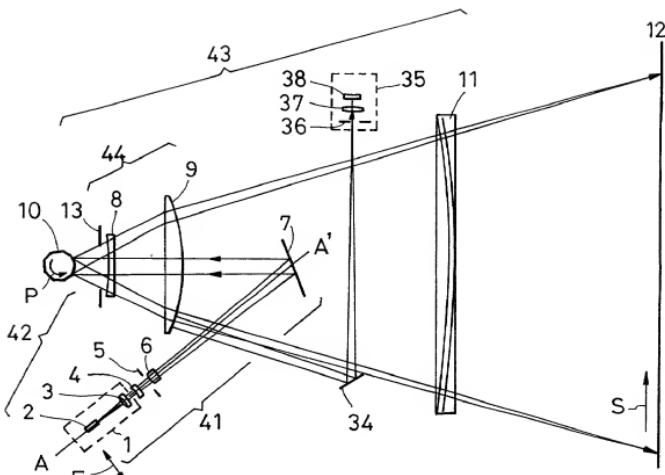


FIG. 1B



FIG. IC

SECTION TAKEN ALONG LINE AA'

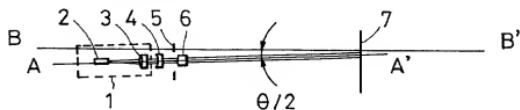
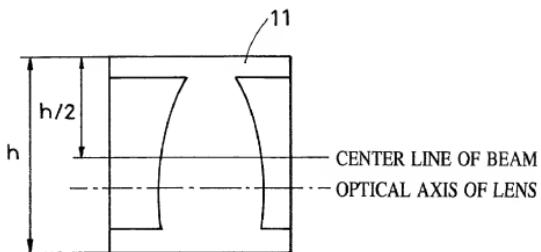
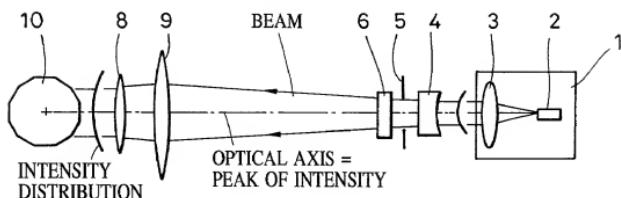


FIG. 2

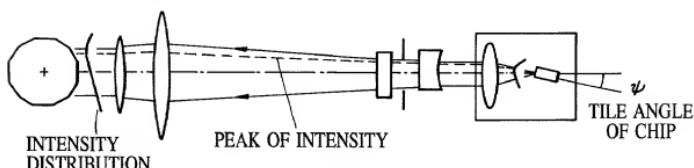


**FIG. 3A**

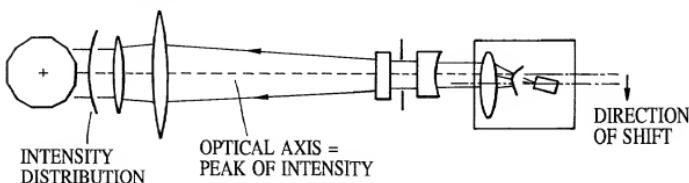
WITH SEMICONDUCTOR LASER CHIP NOT TILTED

**FIG. 3B**

WITH SEMICONDUCTOR LASER CHIP TILTED

**FIG. 3C**

WITH SEMICONDUCTOR LASER CHIP SHIFTED



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FIG. 4A

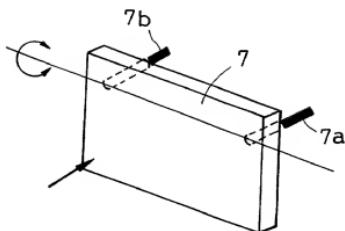


FIG. 4B

INCIDENT LIGHT

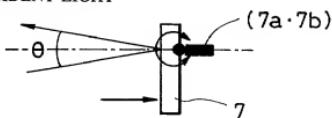


FIG. 5A

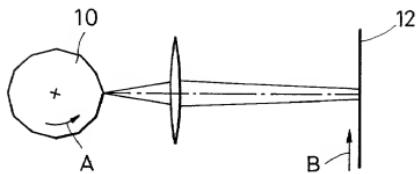


FIG. 5B

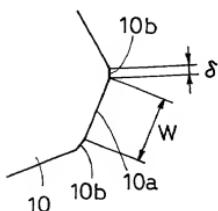


FIG. 6

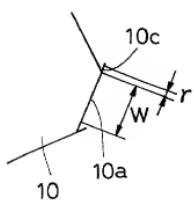


FIG. 7A

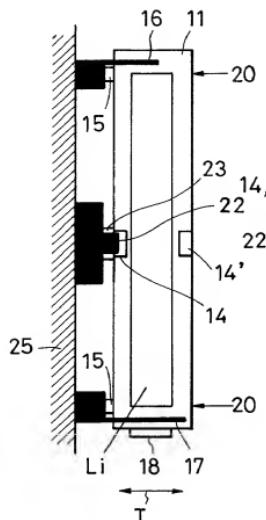


FIG. 7B

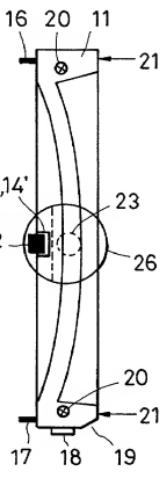


FIG. 7C

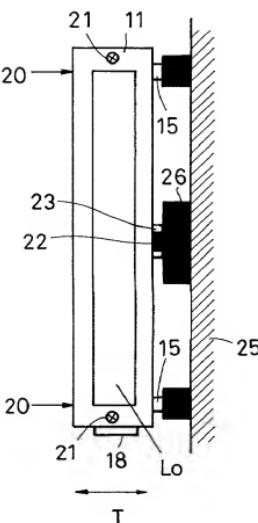


FIG. 7D

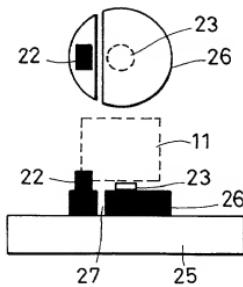


FIG. 8

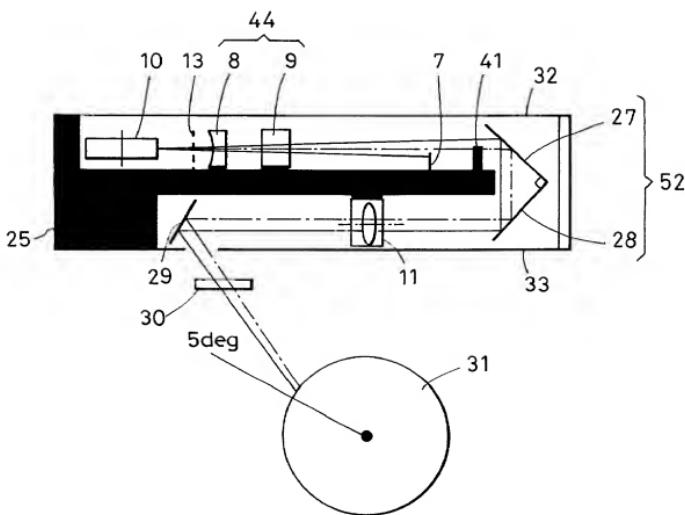
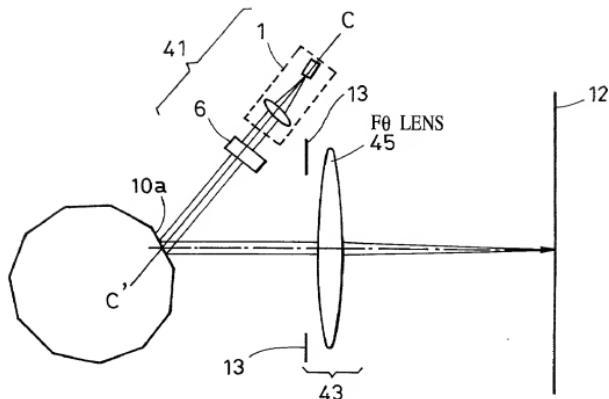


FIG. 9A



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FIG. 9B

SECTION IN SUB-SCAN OPERATION TAKEN ALONG LINE CC'

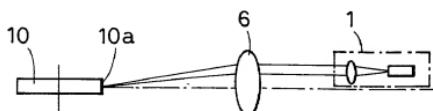


FIG. 10

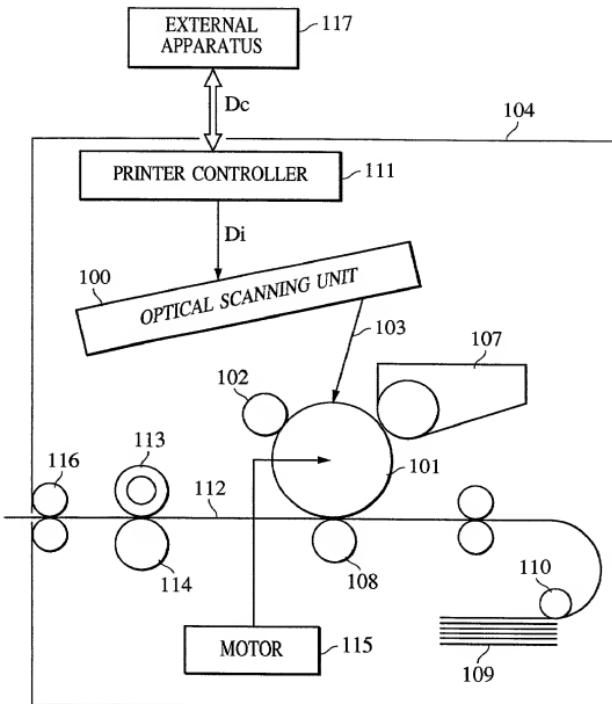


FIG. II

